

1.0 INTRODUCTION

This drawing describes the requirements for procuring the unpackaged integrated circuit die used in the manufacture of P/N 54ACT240, a Octal Buffer/Line Driver w/3 State Outputs. All changes and/or substitutions to the procured parts are subject to prior approval by Interpoint. This specification is to be used with GEN-008.

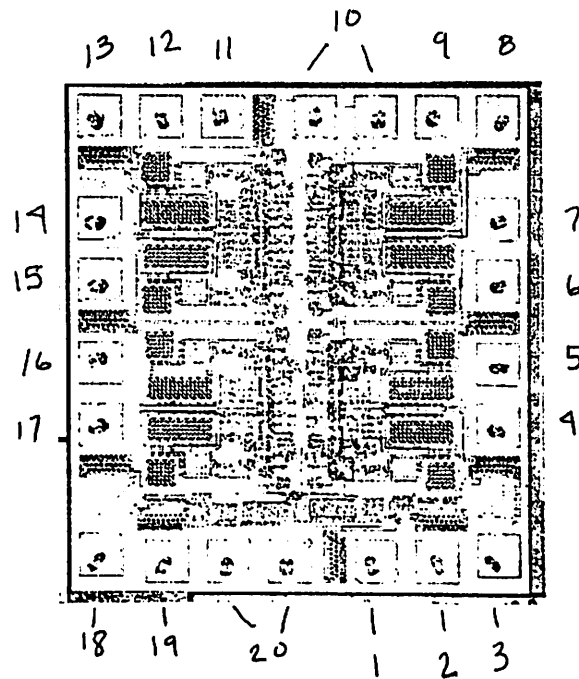
2.0 APPLICABLE DOCUMENTS

- GEN-008 Integrated Circuit Dice
- QA-029 Element Evaluation Procedure

3.0 REQUIREMENTS

3.1 Mechanical/Physical Characteristics

Each die shall be configured per Figure 1 or 2 and Figure 3.



- NOTES: 1. Mfr. Motorola  
 2. Die size .053 x .048 ± .005  
 3. Metallization - Topside: Al; Backside: Au or Si

FIGURE 1 - DIE CONFIGURATION

**interpoint**

10301 WILLOWS ROAD, REDMOND, WA 98052

SIZE <b>A</b>	CAGE NO. <b>50821</b>	DRAWING NO. 85395	REV A
SCALE		SHEET 2 OF 5	

300-07166